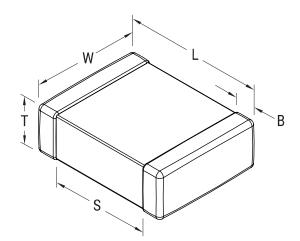


C1206X183KATAC7210

SMD Comm X8G HT150C Flex, Ceramic, 0.018 uF, 10%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1206, 1.5 mm



Click here for the 3D model.

General Information	ormation	
Series	SMD Comm X8G HT150C Flex	
Style	SMD Chip	
Description	SMD, MLCC, High Temperature, Ultra-Stable	
Features	High Temperature, Ultra-Stable	
RoHS	Yes	
Termination	Flexible Termination	
Marking	No	
AEC-Q200	No	
Typical Component Weight	36 mg	
Shelf Life	78 Weeks	
MSL	1	

Dimensions	
Chip Size	1206
L	3.3mm +/-0.4mm
W	1.6mm +/-0.35mm
т	1.6mm +/-0.20mm
S	1.5mm MIN
В	0.6mm +/-0.25mm

Packaging Specifications Packaging T&R, 330mm, Plastic Tape

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Packaging Quantity	8000

Specifications	
Capacitance	0.018 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	10%
Voltage DC	250 VDC
Dielectric Withstanding Voltage	625 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	55.5556 GOhms

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